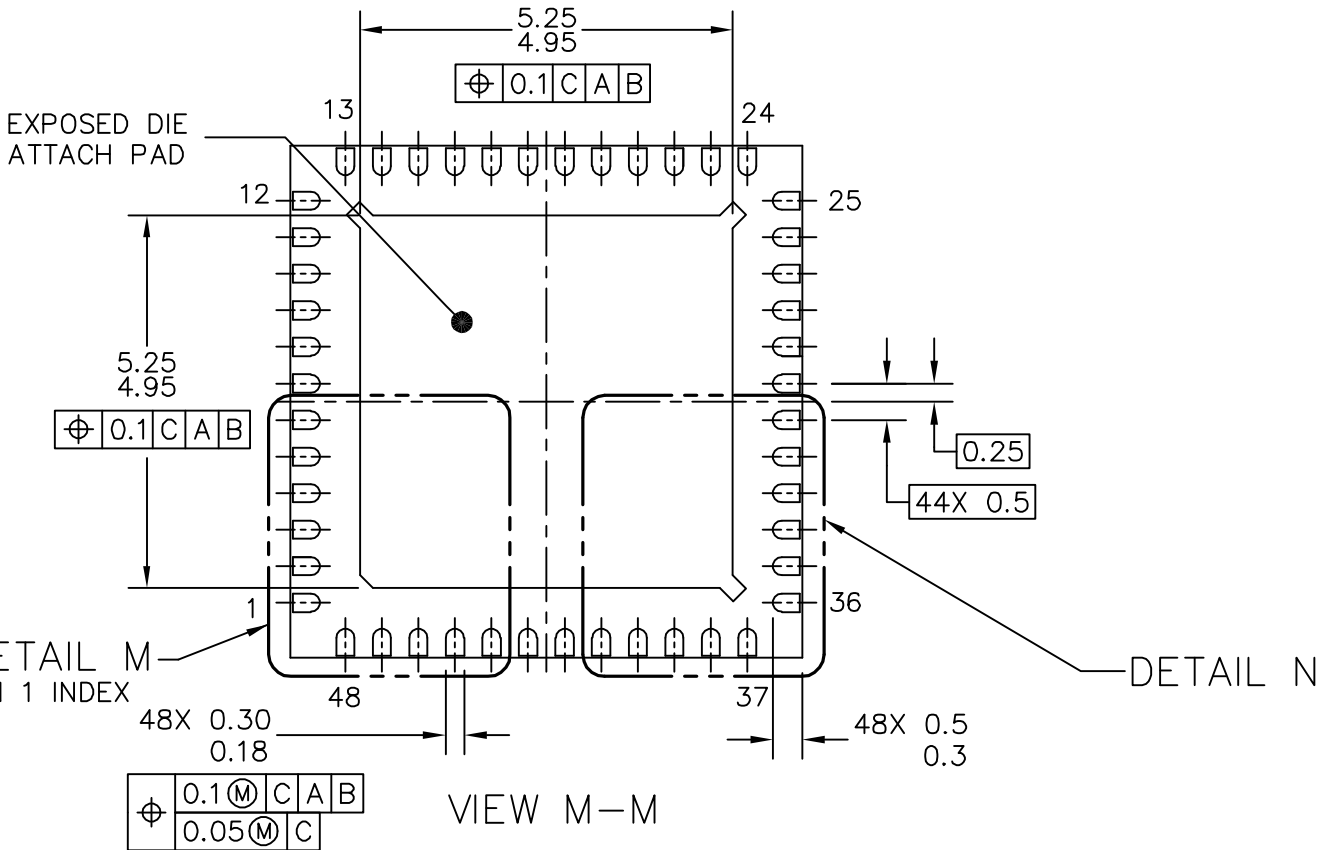
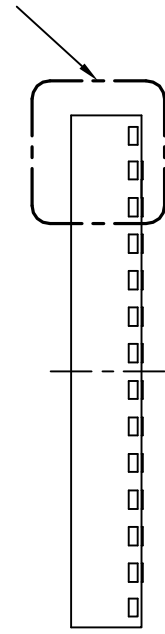
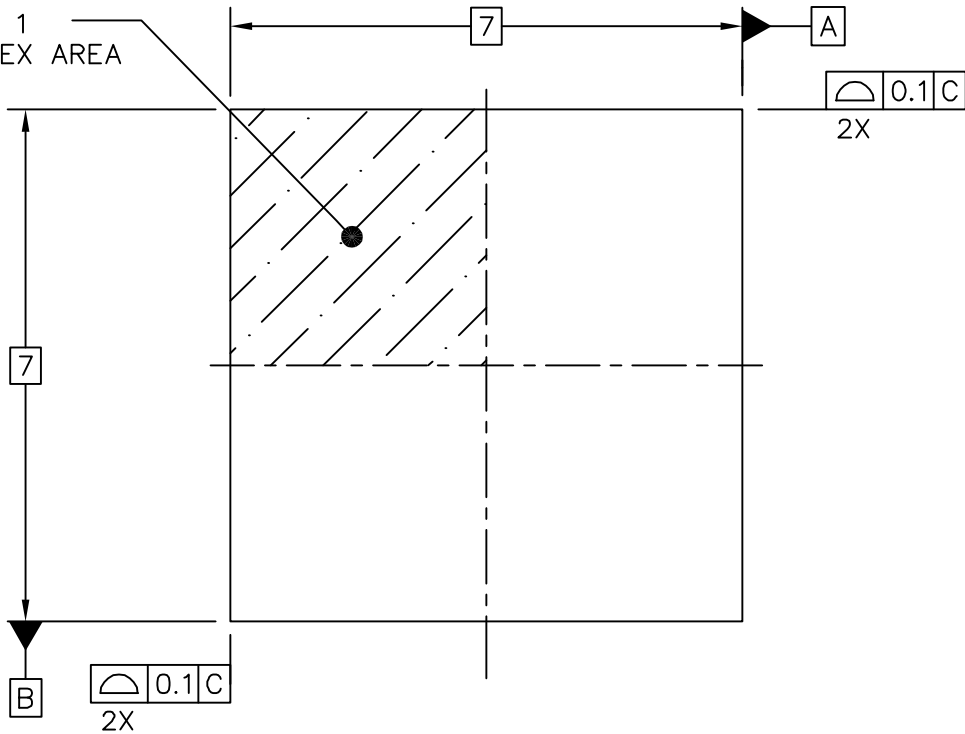


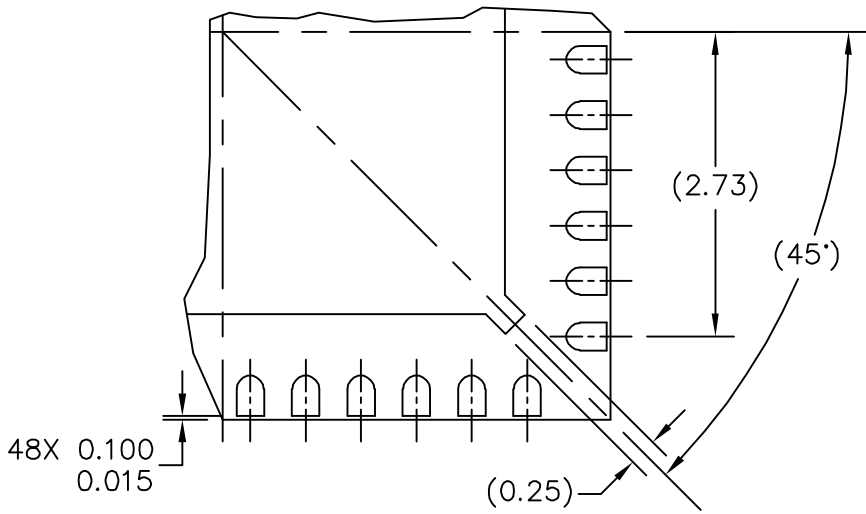


PIN 1 INDEX AREA

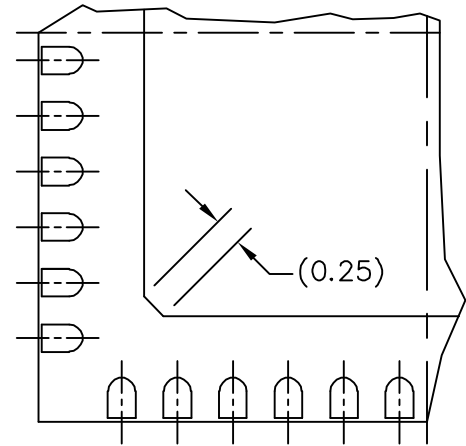


VIEW M-M

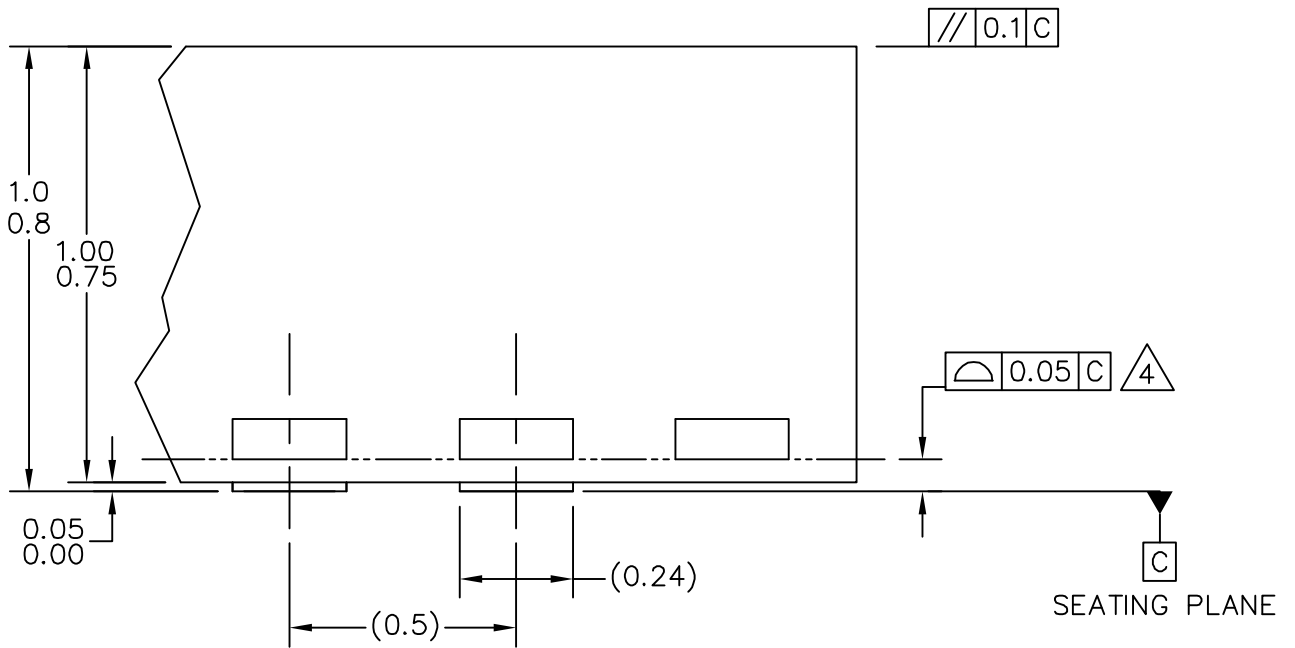
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<b>TITLE:</b> QFN, THERMALLY ENHANCED, 7 X 7 X 1, 0.5 PITCH, 48 TERMINAL	DOCUMENT NO: 98ARH99048A      REV: J STANDARD: JEDEC-MO-220 VKKD-2 SOT619-15      25 DEC 2015	



DETAIL N  
PREFERRED CORNER CONFIGURATION



DETAIL M  
PREFERRED PIN 1 BACKSIDE IDENTIFIER




DETAIL G  
VIEW ROTATED 90° CW

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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4.  COPLANARITY APPLIES TO LEADS, CORNER LEADS, AND DIE ATTACH PAD.
5. MIN METAL GAP SHOULD BE 0.2MM.

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TITLE: QFN, THERMALLY ENHANCED, 7 X 7 X 1, 0.5 PITCH, 48 TERMINAL	DOCUMENT NO: 98ARH99048A      REV: J	
	STANDARD: JEDEC-MO-220 VKKD-2	
	SOT619-15      25 DEC 2015	